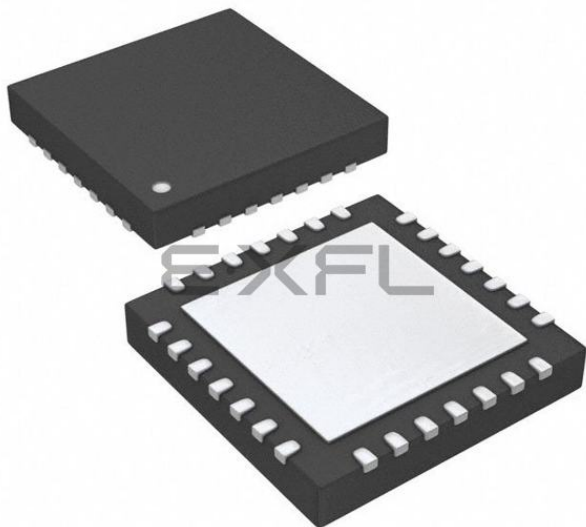




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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f722-e-mv

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PIC16(L)F722/3/4/6/7

TABLE 1-1: PIC16(L)F722/3/4/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB4/AN11/CPS4	RB4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN11	AN	—	A/D Channel 11 input.
	CPS4	AN	—	Capacitive sensing input 4.
RB5/AN13/CPS5/T1G	RB5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN13	AN	—	A/D Channel 13 input.
	CPS5	AN	—	Capacitive sensing input 5.
	T1G	ST	—	Timer1 Gate input.
RB6/ICSPCLK/ICDCLK	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPCLK	ST	—	Serial Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RB7/ICSPDAT/ICDDAT	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	—	In-Circuit Data I/O.
RC0/T1OSO/T1CKI	RC0	ST	CMOS	General purpose I/O.
	T1OSO	XTAL	XTAL	Timer1 oscillator connection.
	T1CKI	ST	—	Timer1 clock input.
RC1/T1OSI/CCP2	RC1	ST	CMOS	General purpose I/O.
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
RC2/CCP1	RC2	ST	CMOS	General purpose I/O.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
RC3/SCK/SCL	RC3	ST	CMOS	General purpose I/O.
	SCK	ST	CMOS	SPI clock.
	SCL	I ² C	OD	I ² C clock.
RC4/SDI/SDA	RC4	ST	CMOS	General purpose I/O.
	SDI	ST	—	SPI data input.
	SDA	I ² C	OD	I ² C data input/output.
RC5/SDO	RC5	ST	CMOS	General purpose I/O.
	SDO	—	CMOS	SPI data output.
RC6/TX/CK	RC6	ST	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
RC7/RX/DT	RC7	ST	CMOS	General purpose I/O.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
RD0/CPS8	RD0	ST	CMOS	General purpose I/O.
	CPS8	AN	—	Capacitive sensing input 8.
RD1/CPS9	RD1	ST	CMOS	General purpose I/O.
	CPS9	AN	—	Capacitive sensing input 9.
RD2/CPS10	RD2	ST	CMOS	General purpose I/O.
	CPS10	AN	—	Capacitive sensing input 10.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I²C = Schmitt Trigger input with I²C
HV = High Voltage XTAL = Crystal levels

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3.1 MCLR

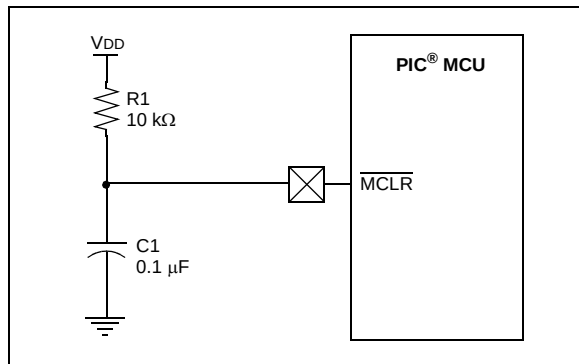
The PIC16(L)F722/3/4/6/7 has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a Reset does not drive the MCLR pin low.

Voltages applied to the pin that exceed its specification can result in both MCLR Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 3-2, is suggested.

An internal MCLR option is enabled by clearing the MCLRE bit in the Configuration Word register. When MCLRE = 0, the Reset signal to the chip is generated internally. When the MCLRE = 1, the RE3/MCLR pin becomes an external Reset input. In this mode, the RE3/MCLR pin has a weak pull-up to VDD. In-Circuit Serial Programming is not affected by selecting the internal MCLR option.

FIGURE 3-2: RECOMMENDED MCLR CIRCUIT



3.2 Power-on Reset (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. A maximum rise time for VDD is required. See **Section 23.0 “Electrical Specifications”** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until VDD reaches VBOR (see **Section 3.5 “Brown-Out Reset (BOR)”**).

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607, *Power-up Trouble Shooting* (DS00607).

3.3 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from the WDT oscillator. For more information, see **Section 7.3 “Internal Clock Modes”**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit, PWRTÉ, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip and vary due to:

- VDD variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 23.0 “Electrical Specifications”**).

Note: The Power-up Timer is enabled by the PWRTÉ bit in the Configuration Word.

3.4 Watchdog Timer (WDT)

The WDT has the following features:

- Shares an 8-bit prescaler with Timer0
- Time-out period is from 17 ms to 2.2 seconds, nominal
- Enabled by a Configuration bit

WDT is cleared under certain conditions described in Table 3-1.

3.4.1 WDT OSCILLATOR

The WDT derives its time base from 31 kHz internal oscillator.

Note: When the Oscillator Start-up Timer (OST) is invoked, the WDT is held in Reset, because the WDT Ripple Counter is used by the OST to perform the oscillator delay count. When the OST count has expired, the WDT will begin counting (if enabled).

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: first, PWRT time out is invoked after POR has expired, then OST is activated after the PWRT time out has expired. The total time out will vary based on oscillator configuration and PWRTE bit status. For example, in EC mode with PWRTE bit = 1 (PWRT disabled), there will be no time out at all. Figure 3-4, Figure 3-5 and Figure 3-6 depict time-out sequences.

Since the time outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time outs will expire. Then, bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC16(L)F722/3/4/6/7 device operating in parallel.

Table 3-3 shows the Reset conditions for some special registers.

3.7 Power Control (PCON) Register

The Power Control (PCON) register has two Status bits to indicate what type of Reset that last occurred.

Bit 0 is $\overline{\text{BOR}}$ (Brown-out Reset). $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOR}} = 0$, indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ Status bit is a “don’t care” and is not necessarily predictable if the brown-out circuit is disabled ($\text{BOREN}<1:0> = 00$ in the Configuration Word register).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a ‘0’ on Power-on Reset and unaffected otherwise. The user must write a ‘1’ to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is ‘0’, it will indicate that a Power-on Reset has occurred (i.e., VDD may have gone too low).

For more information, see Section 3.5 “Brown-Out Reset (BOR)”.

TABLE 3-2: TIME OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{\text{PWRTE}} = 0$	$\overline{\text{PWRTE}} = 1$	$\overline{\text{PWRTE}} = 0$	$\overline{\text{PWRTE}} = 1$	
XT, HS, LP ⁽¹⁾	$\text{TPWRT} + 1024 \cdot \text{TOSC}$	$1024 \cdot \text{TOSC}$	$\text{TPWRT} + 1024 \cdot \text{TOSC}$	$1024 \cdot \text{TOSC}$	$1024 \cdot \text{TOSC}$
RC, EC, INTOSC	TPWRT	—	TPWRT	—	—

Note 1: LP mode with T1OSC disabled.

TABLE 3-3: RESET BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	u	1	1	Power-on Reset
1	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep

Legend: u = unchanged, x = unknown

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TABLE 3-4: INITIALIZATION CONDITION FOR REGISTERS (CONTINUED)

Register	Address	Power-on Reset/ Brown-out Reset ⁽¹⁾	MCLR Reset/ WDT Reset	Wake-up from Sleep through Interrupt/Time out
PCON	8Eh	---- --qq	---- --uu ^(1,5)	---- --uu
T1GCON	8Fh	0000 0x00	uuuu uxuu	uuuu uxuu
OSCCON	90h	--10 qq--	--10 qq--	--uu qq--
OSCTUNE	91h	--00 0000	--uu uuuu	--uu uuuu
PR2	92h	1111 1111	1111 1111	uuuu uuuu
SSPAD	93h	0000 0000	0000 0000	uuuu uuuu
SSPMASK	93h	1111 1111	1111 1111	uuuu uuuu
SSPSTAT	94h	0000 0000	0000 0000	uuuu uuuu
WPUB	95h	1111 1111	1111 1111	uuuu uuuu
IOCB	96h	0000 0000	0000 0000	uuuu uuuu
TXSTA	98h	0000 -010	0000 -010	uuuu -uuu
SPBRG	99h	0000 0000	0000 0000	uuuu uuuu
APFCON	9Ch	---- --00	---- --00	---- --uu
FVRCON	9Dh	q000 --00	q000 --00	uuuu --uu
ADCON1	9Fh	-000 --00	-000 --00	-uuu --uu
CPSCON0	108h	0--- 0000	0--- 0000	u--- uuuu
CPSCON1	109h	---- 0000	---- 0000	---- uuuu
PMDATL	10Ch	xxxx xxxx	xxxx xxxx	uuuu uuuu
PMADRL	10Dh	xxxx xxxx	xxxx xxxx	uuuu uuuu
PMDATH	10Eh	--xx xxxx	--xx xxxx	--uu uuuu
PMADRH	10Fh	---x xxxx	---x xxxx	---u uuuu
ANSELA	185h	--11 1111	--11 1111	--uu uuuu
ANSELB	186h	--11 1111	--11 1111	--uu uuuu
ANSELD ⁽⁶⁾	188h	1111 1111	1111 1111	uuuu uuuu
ANSELE	189h	---- -111	---- -111	---- -uuu
PMCON1	18Ch	1--- ---0	1--- ---0	u--- ---u

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

- Note**
- 1: If V_{DD} goes too low, Power-on Reset will be activated and registers will be affected differently.
 - 2: One or more bits in INTCON and/or PIR1 and PIR2 will be affected (to cause wake-up).
 - 3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).
 - 4: See Table 3-5 for Reset value for specific condition.
 - 5: If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.
 - 6: PIC16F724/727/PIC16LF724/727 only.

TABLE 3-5: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	0001 1xxx	---- --0x
MCLR Reset during normal operation	0000h	000u uuuu	---- --uu
MCLR Reset during Sleep	0000h	0001 0uuu	---- --uu
WDT Reset	0000h	0000 uuuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	0000h	0001 1xxx	---- --10
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Interrupt Enable bit, GIE, is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

TABLE 3-6: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets ⁽¹⁾
STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$	---- --qq	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition. Shaded cells are not used by Resets.

Note 1: Other (non Power-up) Resets include MCLR Reset and Watchdog Timer Reset during normal operation.

FIGURE 6-2: RA<3:1> BLOCK DIAGRAM

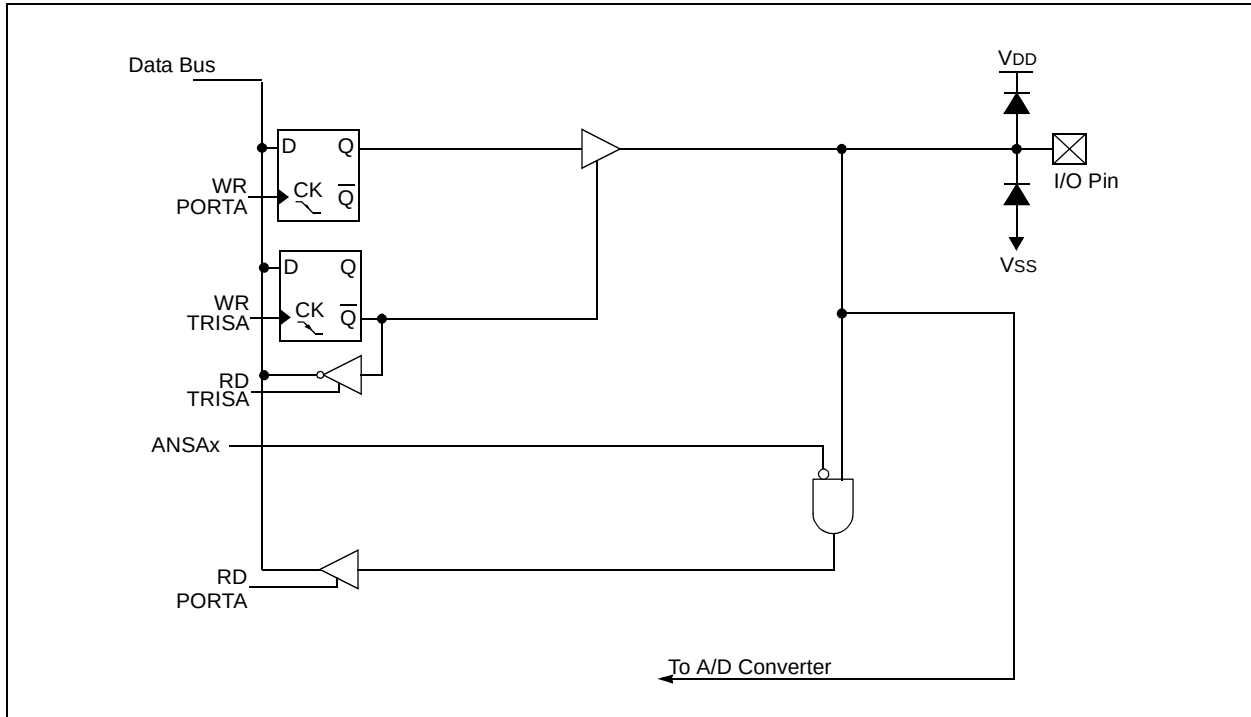
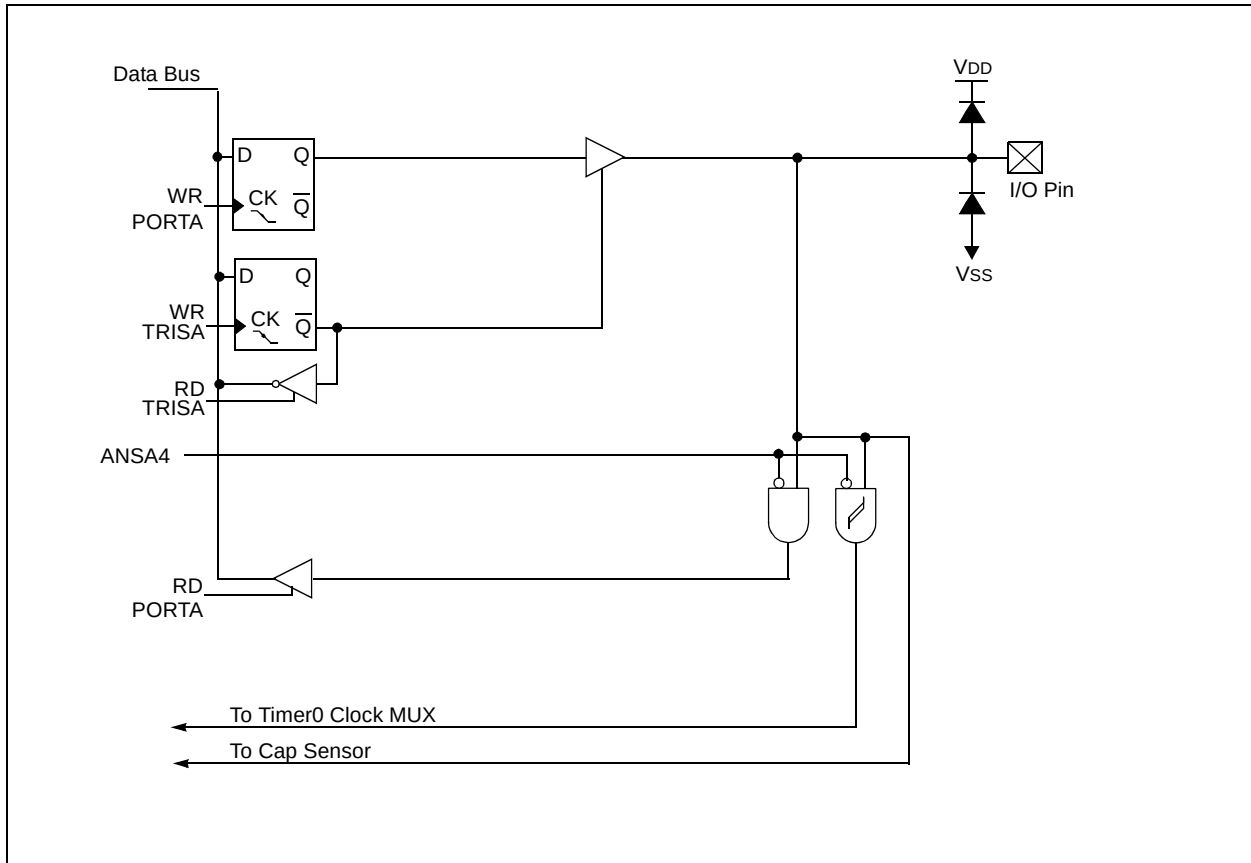


FIGURE 6-3: BLOCK DIAGRAM OF RA4





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REGISTER 9-2: ADCON1: A/D CONTROL REGISTER 1

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0
—	ADCS2	ADCS1	ADCS0	—	—	ADREF1	ADREF0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **ADCS<2:0>:** A/D Conversion Clock Select bits

000 = Fosc/2

001 = Fosc/8

010 = Fosc/32

011 = FRC (clock supplied from a dedicated RC oscillator)

100 = Fosc/4

101 = Fosc/16

110 = Fosc/64

111 = FRC (clock supplied from a dedicated RC oscillator)

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **ADREF<1:0>:** Voltage Reference Configuration bits

0x = VREF is connected to VDD

10 = VREF is connected to external VREF (RA3/AN3)

11 = VREF is connected to internal Fixed Voltage Reference

REGISTER 9-3: ADRES: ADC RESULT REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
ADRES7	ADRES6	ADRES5	ADRES4	ADRES3	ADRES2	ADRES1	ADRES0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 7-0 **ADRES<7:0>:** ADC Result Register bits
8-bit conversion result.

12.1 Timer1 Operation

The Timer1 module is a 16-bit incrementing counter which is accessed through the TMR1H:TMR1L register pair. Writes to TMR1H or TMR1L directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1 is enabled by configuring the TMR1ON and TMR1GE bits in the T1CON and T1GCON registers, respectively. Table 12-1 displays the Timer1 enable selections.

TABLE 12-1: TIMER1 ENABLE SELECTIONS

TMR1ON	TMR1GE	Timer1 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

12.2 Clock Source Selection

The TMR1CS<1:0> and T1OSCEN bits of the T1CON register are used to select the clock source for Timer1. Table 12-2 displays the clock source selections.

12.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected, the TMR1H:TMR1L register pair will increment on multiples of Fosc as determined by the Timer1 prescaler.

12.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When enabled to count, Timer1 is incremented on the rising edge of the external clock input T1CKI or the capacitive sensing oscillator signal. Either of these external clock sources can be synchronized to the microcontroller system clock or they can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1 enabled after POR reset
- Write to TMR1H or TMR1L
- Timer1 is disabled
- Timer1 is disabled (TMR1ON = 0) when T1CKI is high then Timer1 is enabled (TMR1ON= 1) when T1CKI is low.

TABLE 12-2: CLOCK SOURCE SELECTIONS

TMR1CS1	TMR1CS0	T1OSCEN	Clock Source
0	1	x	System Clock (Fosc)
0	0	x	Instruction Clock (Fosc/4)
1	1	x	Capacitive Sensing Oscillator
1	0	0	External Clocking on T1CKI Pin
1	0	1	Oscillator Circuit on T1OSI/T1OSO Pins

REGISTER 14-2: CPSCON1: CAPACITIVE SENSING CONTROL REGISTER 1

U-0	U-0	U-0	U-0	R/W-0 ⁽²⁾	R/W-0	R/W-0	R/W-0
—	—	—	—	CPSCH3	CPSCH2	CPSCH1	CPSCH0
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 7-4 **Unimplemented:** Read as '0'

bit 3-0 **CPSCH<3:0>:** Capacitive Sensing Channel Select bits

If CPSON = 0:

These bits are ignored. No channel is selected.

If CPSON = 1:

0000 = channel 0, (CPS0)
 0001 = channel 1, (CPS1)
 0010 = channel 2, (CPS2)
 0011 = channel 3, (CPS3)
 0100 = channel 4, (CPS4)
 0101 = channel 5, (CPS5)
 0110 = channel 6, (CPS6)
 0111 = channel 7, (CPS7)
 1000 = channel 8, (CPS8⁽¹⁾)
 1001 = channel 9, (CPS9⁽¹⁾)
 1010 = channel 10, (CPS10⁽¹⁾)
 1011 = channel 11, (CPS11⁽¹⁾)
 1100 = channel 12, (CPS12⁽¹⁾)
 1101 = channel 13, (CPS13⁽¹⁾)
 1110 = channel 14, (CPS14⁽¹⁾)
 1111 = channel 15, (CPS15⁽¹⁾)

Note 1: These channels are not implemented on the PIC16F722/723/726/PIC16LF722/723/726.

2: This bit is not implemented on PIC16F722/723/726/PIC16LF722/723/726, Read as '0'

TABLE 14-2: SUMMARY OF REGISTERS ASSOCIATED WITH CAPACITIVE SENSING

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ANSELA	—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	--11 1111	--11 1111
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
ANSELD	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
OPTION_REG	RBP	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	T1SYN	—	TMR1ON	0000 00-0	0000 00-0
T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	1111 1111	1111 1111

Legend: - = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the capacitive sensing module.

PIC16(L)F722/3/4/6/7

FIGURE 16-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)

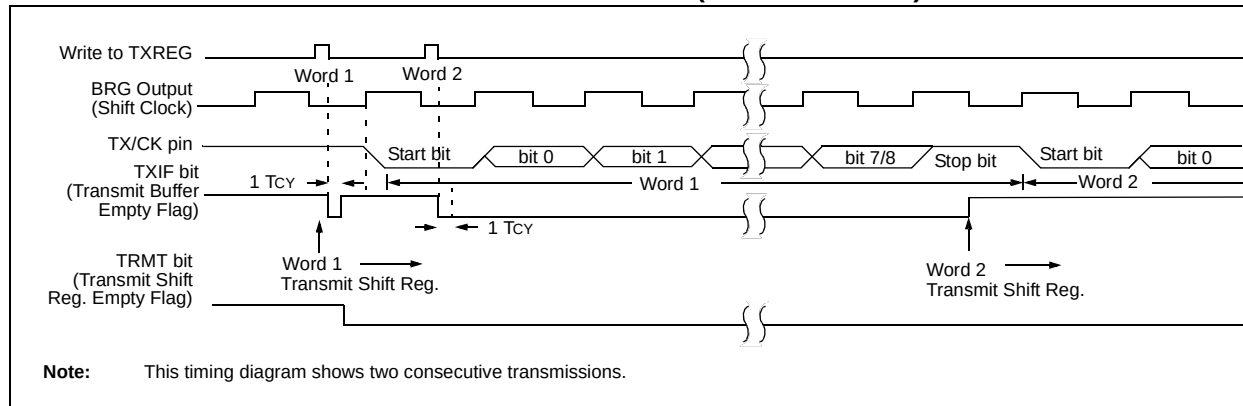


TABLE 16-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Asynchronous Transmission.



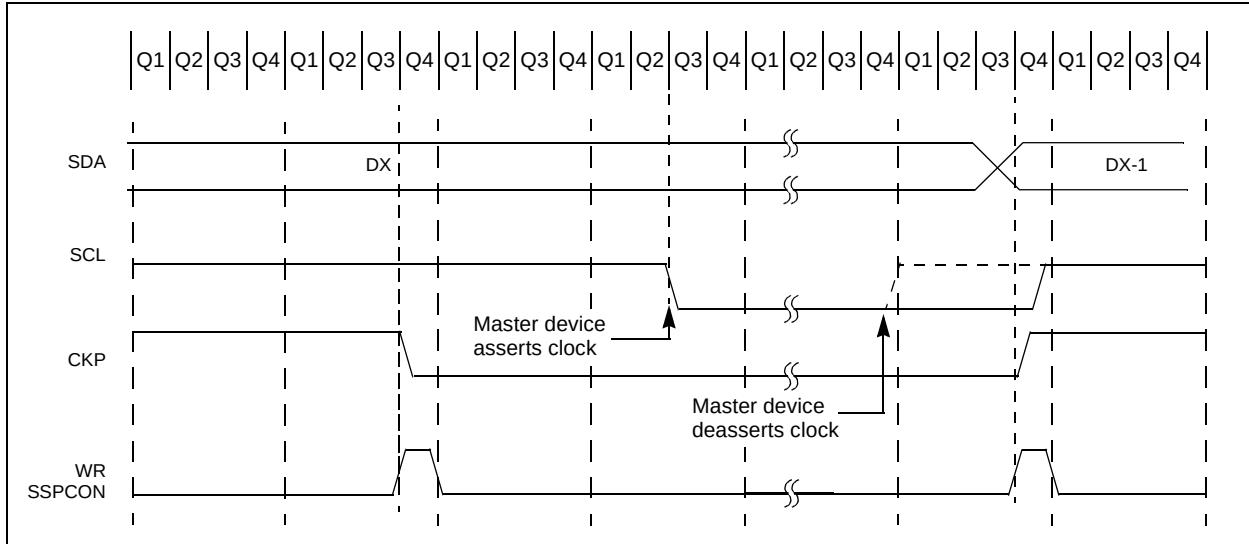
17.2.10 CLOCK SYNCHRONIZATION

When the CKP bit is cleared, the SCL output is held low once it is sampled low. therefore, the CKP bit will not stretch the SCL line until an external I²C master device has already asserted the SCL line low. The SCL output will remain low until the CKP bit is set and all other devices on the I²C bus have released SCL. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCL (Figure 17-14).

17.2.11 SLEEP OPERATION

While in Sleep mode, the I²C module can receive addresses of data, and when an address match or complete byte transfer occurs, wake the processor from Sleep (if SSP interrupt is enabled).

FIGURE 17-14: CLOCK SYNCHRONIZATION TIMING



19.2 Wake-up Using Interrupts

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will not be cleared, the $\overline{TO}$ bit will not be set and the $\overline{PD}$ bit will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWD instruction should be executed before a SLEEP instruction.

FIGURE 19-1: WAKE-UP FROM SLEEP THROUGH INTERRUPT

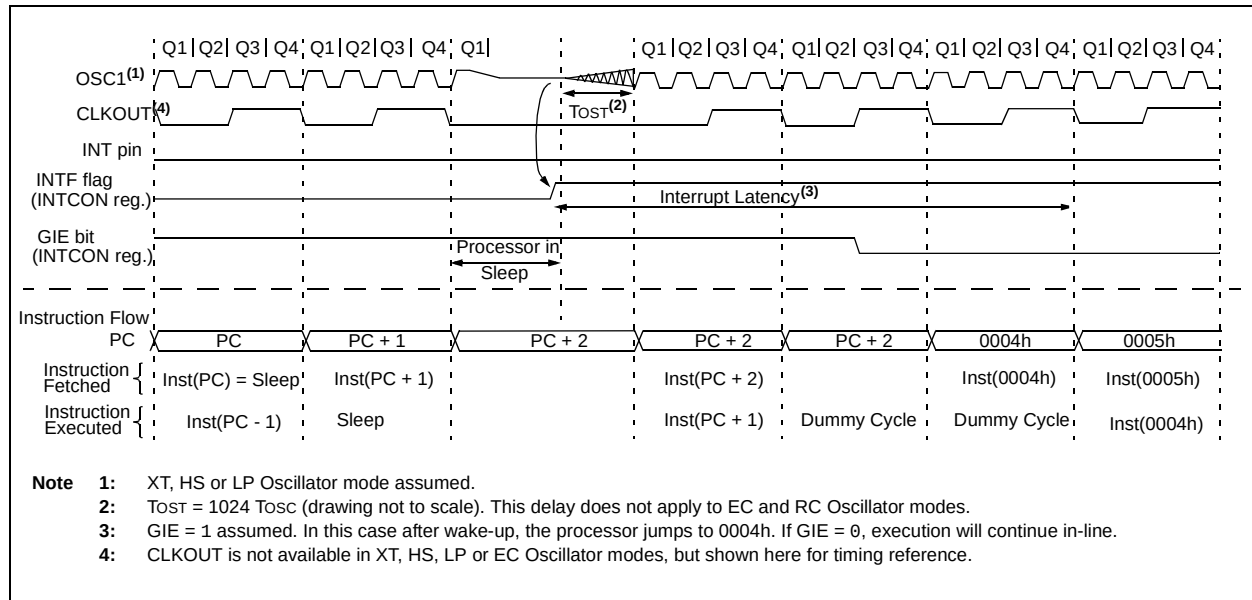


TABLE 19-1: SUMMARY OF REGISTERS ASSOCIATED WITH POWER-DOWN MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
IOCB	IOCB7	IOCB6	IOCB5	IOCB4	IOCB3	IOCB2	IOCB1	IOCB0	0000 0000	0000 0000
INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 0000	0000 0000
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIE2	—	—	—	—	—	—	—	CCP2IE	---- --0	---- --0
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIR2	—	—	—	—	—	—	—	CCP2IF	---- --0	---- --0

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used in Power-Down mode.

PIC16(L)F722/3/4/6/7

23.3 DC Characteristics: PIC16(L)F722/3/4/6/7-I/E (Power-Down) (Continued)

PIC16LF722/3/4/6/7			Standard Operating Conditions (unless otherwise stated)					
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F722/3/4/6/7			Standard Operating Conditions (unless otherwise stated)					
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
D027	Power-down Base Current (IPD) ⁽²⁾							
		—	0.06	0.7	5.0	μA	1.8	A/D Current (Note 1, Note 4), no conversion in progress
		—	0.08	1.0	5.5	μA	3.0	
D027		—	6	10.7	18	μA	1.8	A/D Current (Note 1, Note 4), no conversion in progress
		—	7	10.6	20	μA	3.0	
		—	7.2	11.9	22	μA	5.0	
D027A		—	250	400	—	μA	1.8	A/D Current (Note 1, Note 4), conversion in progress
		—	250	400	—	μA	3.0	
D027A		—	280	430	—	μA	1.8	A/D Current (Note 1, Note 4, Note 5), conversion in progress
		—	280	430	—	μA	3.0	
		—	280	430	—	μA	5.0	
D028		—	2.2	3.2	14.4	μA	1.8	Cap Sense Low Power Oscillator mode
		—	3.3	4.4	15.6	μA	3.0	
D028		—	6.5	13	21	μA	1.8	Cap Sense Low Power Oscillator mode
		—	8	14	23	μA	3.0	
		—	8	14	25	μA	5.0	
D028A		—	4.2	6	17	μA	1.8	Cap Sense Medium Power Oscillator mode
		—	6	7	18	μA	3.0	
D028A		—	8.5	15.5	23	μA	1.8	Cap Sense Medium Power Oscillator mode
		—	11	17	24	μA	3.0	
		—	11	18	27	μA	5.0	
D028B		—	12	14	25	μA	1.8	Cap Sense High Power Oscillator mode
		—	32	35	44	μA	3.0	
D028B		—	16	20	31	μA	1.8	Cap Sense High Power Oscillator mode
		—	36	41	50	μA	3.0	
		—	42	49	58	μA	5.0	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.
- 2:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.
- 3:** Fixed Voltage Reference is automatically enabled whenever the BOR is enabled
- 4:** A/D oscillator source is FRC
- 5:** 0.1 μF capacitor on VCAP (RA0).

PIC16(L)F722/3/4/6/7

FIGURE 24-3: PIC16F722/3/4/6/7 TYPICAL I_{DD} vs. F_{OSC} OVER V_{DD} , EC MODE, $V_{CAP} = 0.1 \mu F$

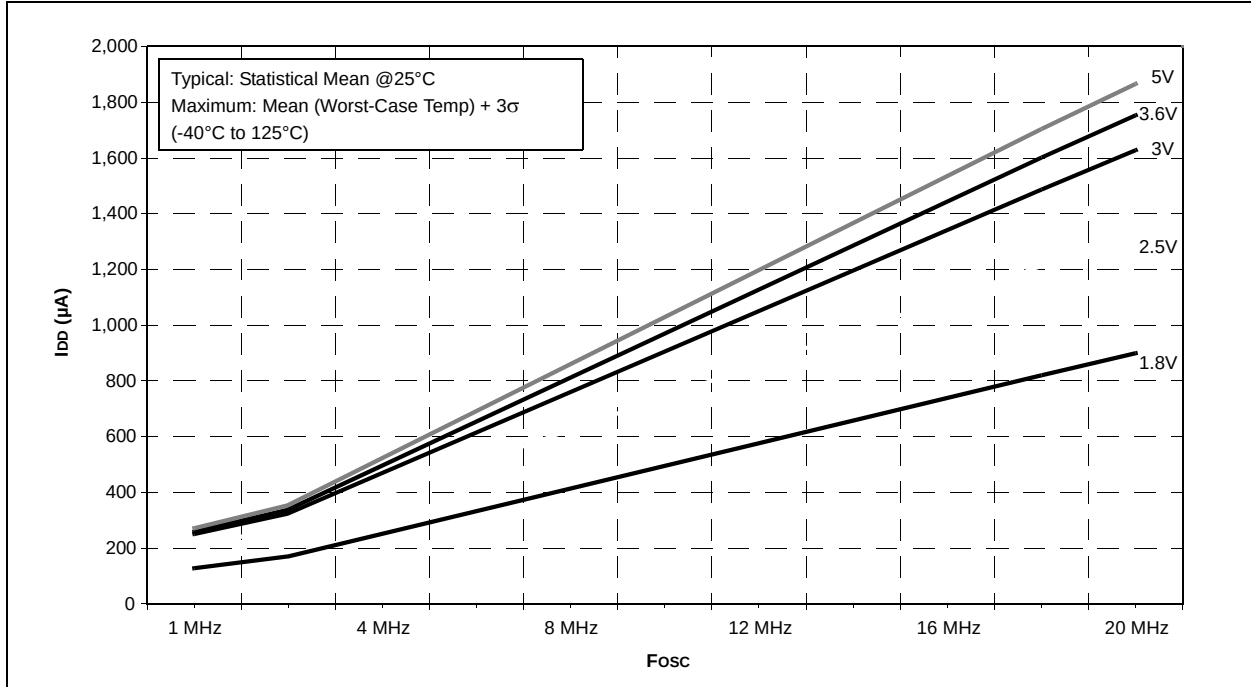
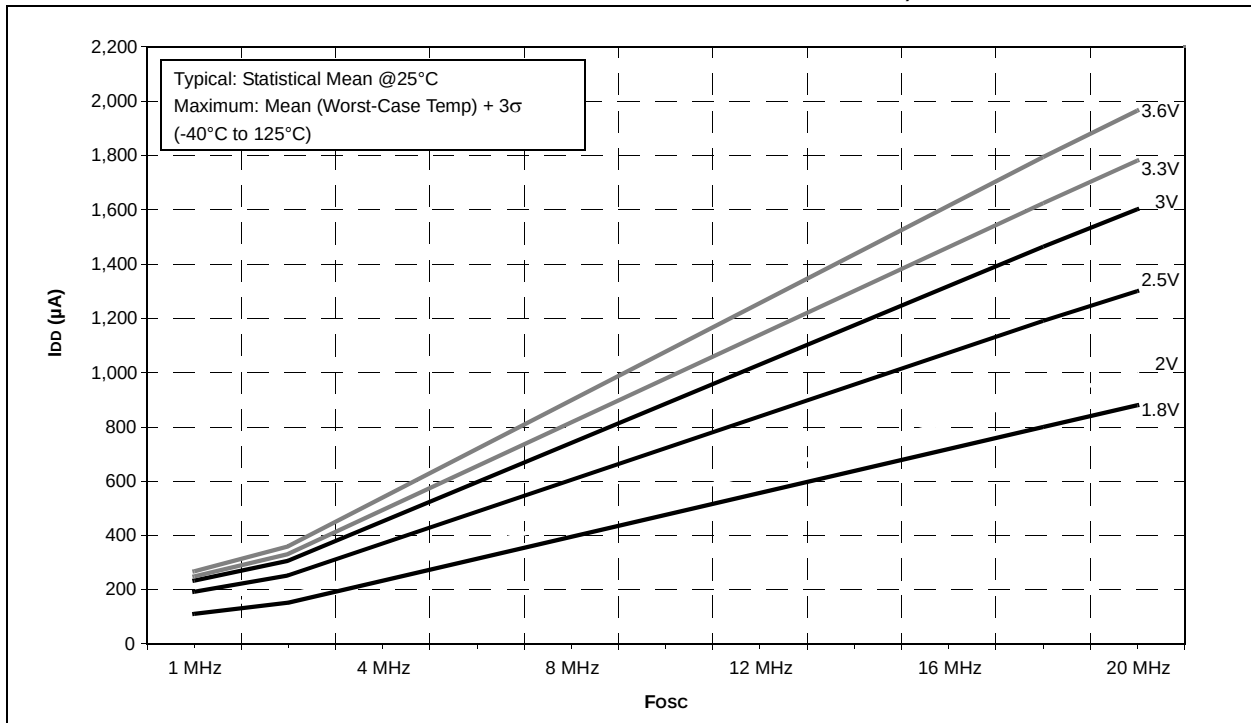


FIGURE 24-4: PIC16LF722/3/4/6/7 TYPICAL I_{DD} vs. F_{OSC} OVER V_{DD} , EC MODE



PIC16(L)F722/3/4/6/7

FIGURE 24-13: PIC16F722/3/4/6/7 MAXIMUM I_{DD} vs. V_{DD} OVER F_{OSC} , XT MODE, $V_{CAP} = 0.1 \mu F$

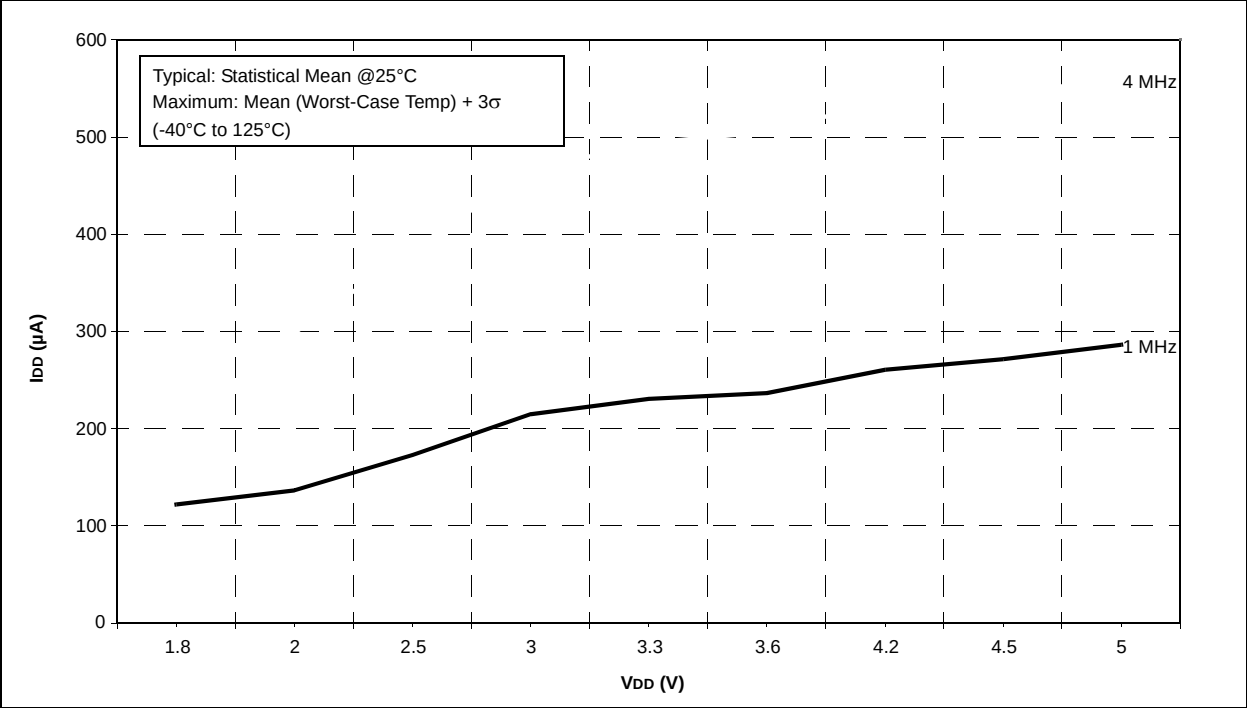
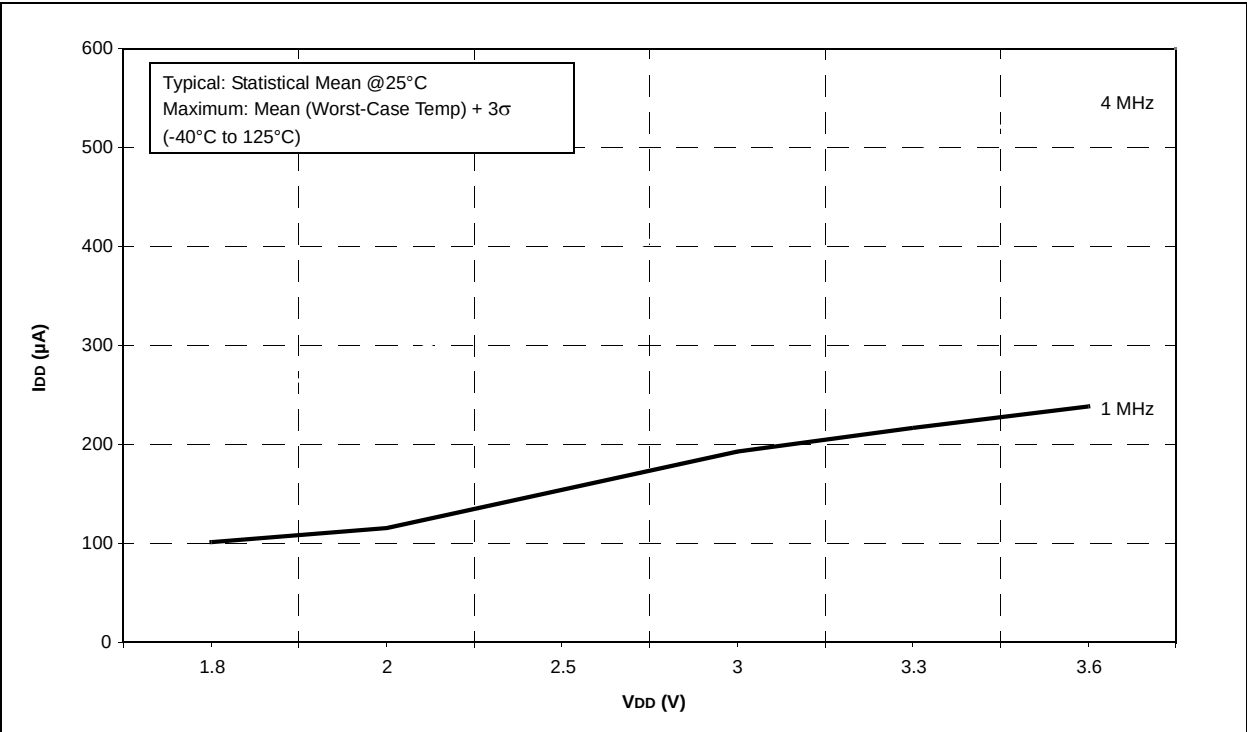


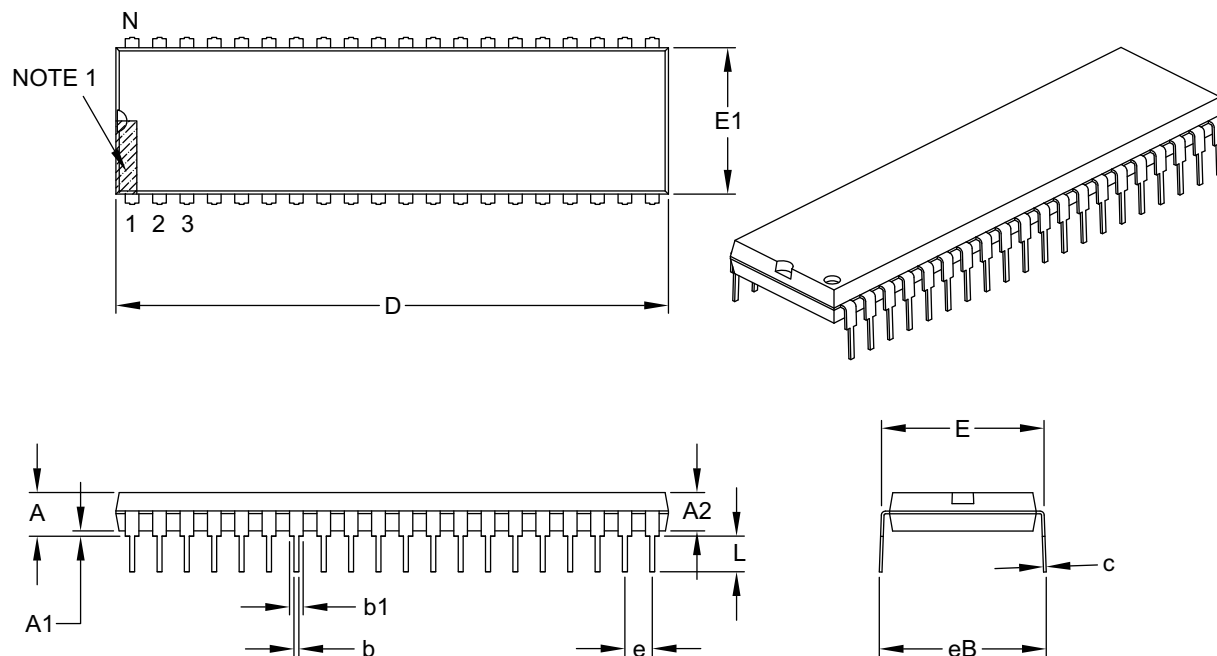
FIGURE 24-14: PIC16LF722/3/4/6/7 MAXIMUM I_{DD} vs. V_{DD} OVER F_{OSC} , XT MODE



PIC16(L)F722/3/4/6/7

40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	40		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B